BGA Heat Sink - High Performance maxiFLOW/maxiGRIP-Low Profile





ATS Part#: **ATS-51330D-C1-R0**

Description: 33.00 x 33.00 x 9.50 mm BGA Heat Sink - High Performance maxiFLOW/maxiGRIP-

Low Profile

Heat Sink Type: maxiFLOW
Heat Sink Attachment: maxiGRIP

Equivalent Part Number: ATS-51330D-C2-R0 Discontinued

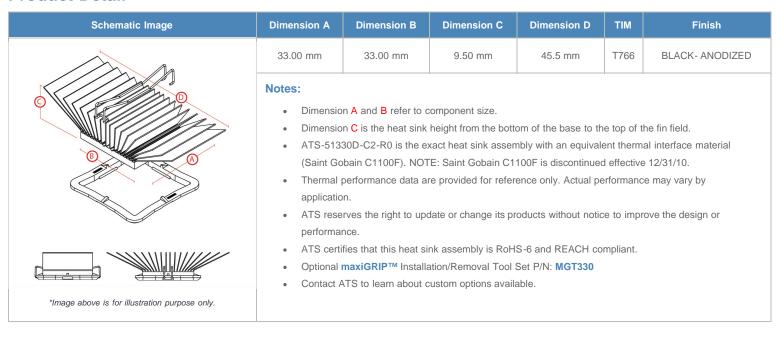
Features & Benefits

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- maxiGRIPTM attachment applies steady, even pressure to the component and does not require holes in the PCB
- Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- · Comes preassembled with high performance, phase changing, thermal interface material
- Designed for low profile components from 1.5 to 2.99mm

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	5.9 °C/W	4.5 °C/W	3.9 °C/W	3.5 °C/W	3.2 °C/W	2.9 °C/W	2.7 °C/W
	Ducted Flow	3.8	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail







^{*}Image above is for illustration purpose only.

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